

# FGL60N170D

## General Description

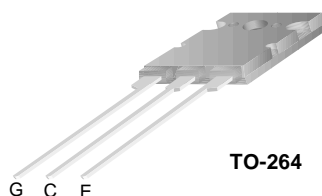
Fairchild's Insulated Gate Bipolar Transistor (IGBT) provides low conduction and switching losses. FGL60N170D is designed for the Induction Heating applications.

## Features

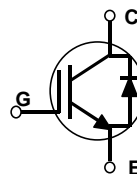
- High Speed Switching
- Low Saturation Voltage :  $V_{CE(sat)} = 5.0\text{ V @ } I_C = 60\text{ A}$
- High Input Impedance
- Built-in Fast Recovery Diode

## Application

Home Appliance, Induction Heater, IH JAR, Micro Wave Oven



TO-264



## Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	FGL60N170D	Units
$V_{CES}$	Collector-Emitter Voltage	1700	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 25$	V
$I_C$	Collector Current @ $T_C = 25^\circ\text{C}$	60	A
	Collector Current @ $T_C = 100^\circ\text{C}$	30	A
$I_{CM(1)}$	Pulsed Collector Current	180	A
$I_F$	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	15	A
$I_{FM}$	Diode Maximum Forward Current	150	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	200	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	80	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for Soldering Purposes from Case for 5 Seconds	300	$^\circ\text{C}$

### Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(\text{IGBT})$	Thermal Resistance, Junction-to-Case	--	0.625	$^\circ\text{C/W}$
$R_{\theta JC}(\text{DIODE})$	Thermal Resistance, Junction-to-Case	--	0.83	$^\circ\text{C/W}$
$R_{\theta A}$	Thermal Resistance, Junction-to-Ambient	--	25	$^\circ\text{C/W}$

**Electrical Characteristics of IGBT**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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**Off Characteristics**

$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 3mA$	1700	--	--	V
$I_{CES}$	Collector Cut-off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	--	--	3.0	mA
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	--	--	$\pm 100$	nA

**On Characteristics**

$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 60mA, V_{CE} = V_{GE}$	3.5	5.0	7.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 60A, V_{GE} = 15V$	-	5.0	6.0	V

**Dynamic Characteristics**

$C_{ies}$	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ $f = 1MHz$	--	2500	--	pF
$C_{oes}$	Output Capacitance		--	220	--	pF
$C_{res}$	Reverse Transfer Capacitance		--	80	--	pF

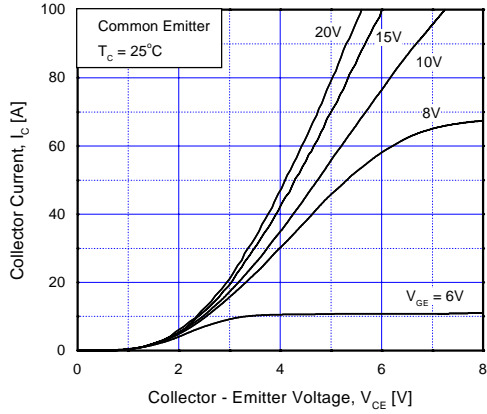
**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600V, I_C = 60A,$ $R_G = 51\Omega, V_{GE} = 15V,$ ResistiveLoad, $T_C = 25^\circ\text{C}$	--	100	200	ns
$t_r$	Rise Time		--	350	700	ns
$t_{d(off)}$	Turn-Off Delay Time		--	200	400	ns
$t_f$	Fall Time		--	100	300	ns
$Q_g$	Total Gate Charge	$V_{CE} = 600V, I_C = 60A,$ $V_{GE} = 15V$	--	120	180	nC
$Q_{ge}$	Gate-Emitter Charge		--	20	30	nC
$Q_{gc}$	Gate-Collector Charge		--	45	70	nC

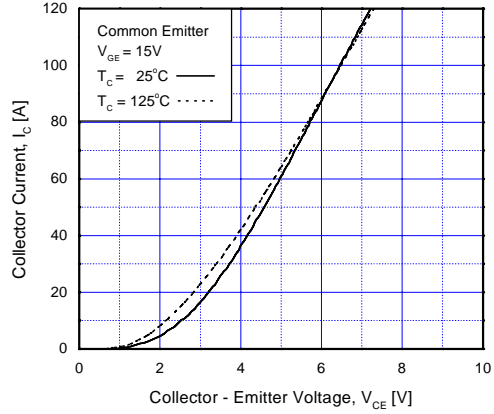
**Electrical Characteristics of DIODE**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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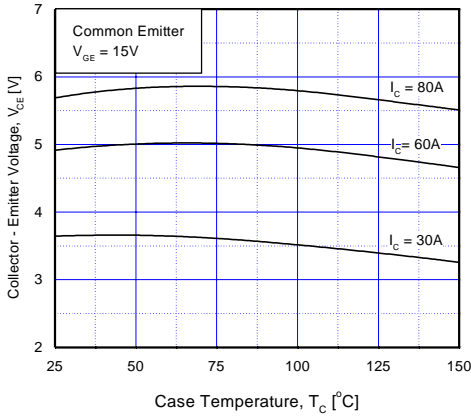
$V_{FM}$	Diode Forward Voltage	$I_F = 15A$	--	1.35	1.6	V
		$I_F = 60A$	--	1.92	2.2	
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 60A, di/dt = 20A/\mu S$	--	0.6	1.0	us
$I_R$	Instantaneous Reverse Current	$V_{RRM} = 1700V$	--	0.3	5	uA
$C_J$	Junction Capacitance	$V_{CE} = 10V, V_{GE} = 0V, f = 1MHz$	--	80	--	pF



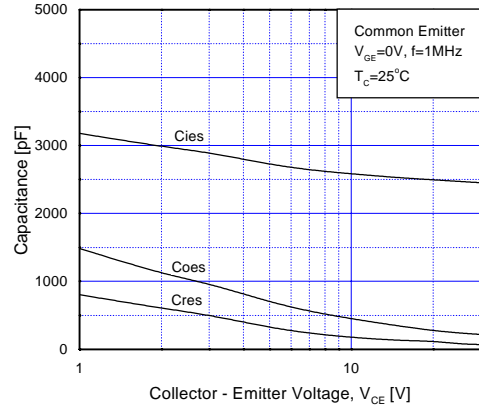
**Fig 1. Typical Output Characteristics**



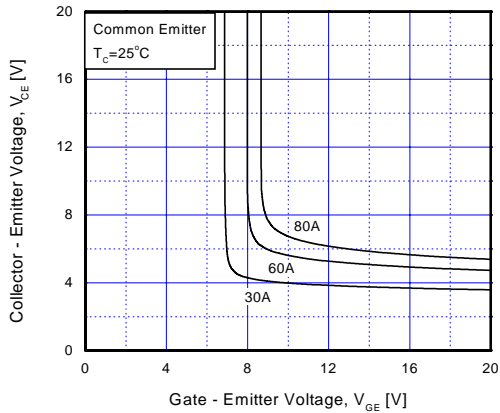
**Fig 2. Typical Saturation Voltage Characteristics**



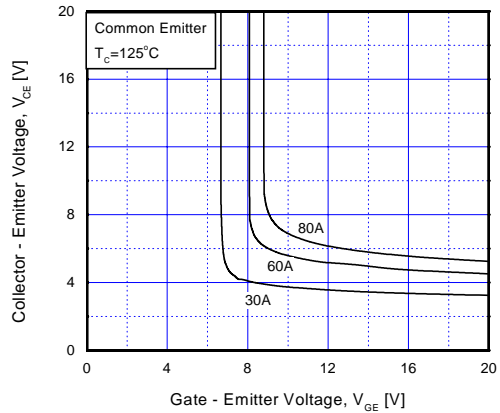
**Fig 3. Collector to Emitter Saturation Voltage vs. Case Temperature**



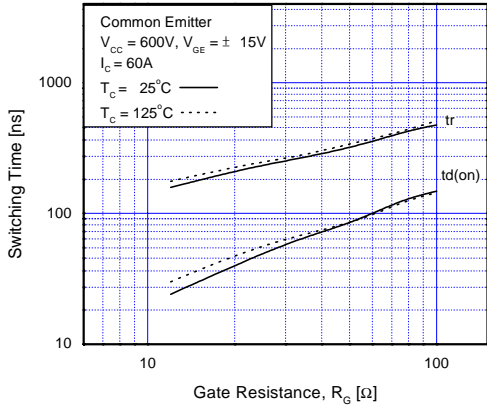
**Fig 4. Typical Capacitance vs. Collector to Emitter Voltage**



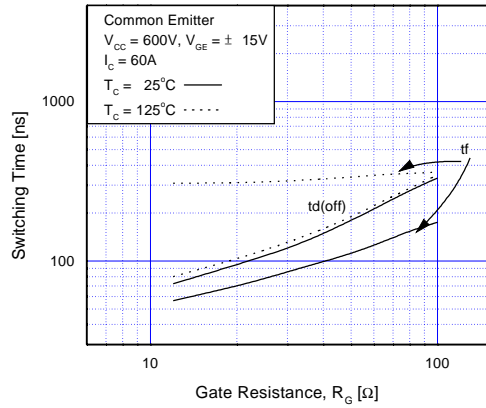
**Fig 5. Saturation Voltage vs.  $V_{GE}$**



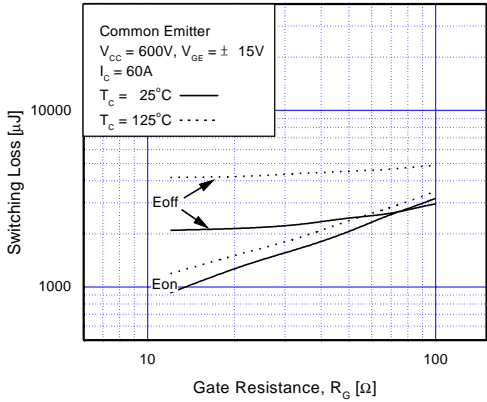
**Fig 6. Saturation Voltage vs.  $V_{GE}$**



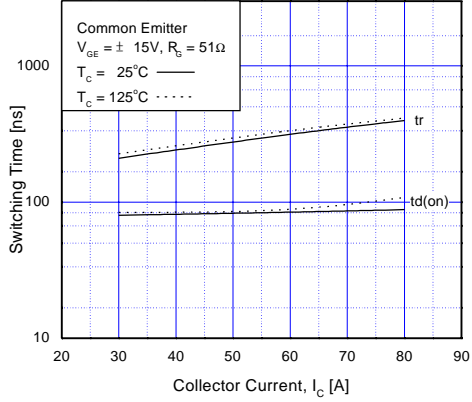
**Fig 7. Turn on Characteristics vs. Gate Resistance**



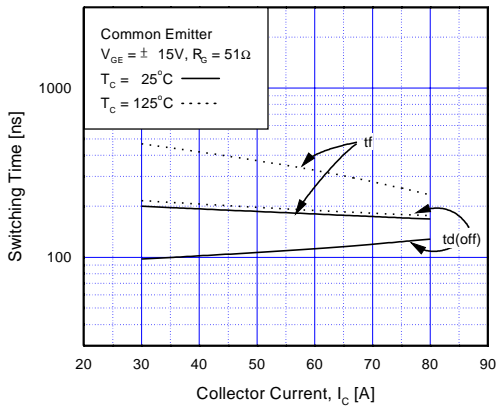
**Fig 8. Turn off Characteristics vs. Gate Resistance**



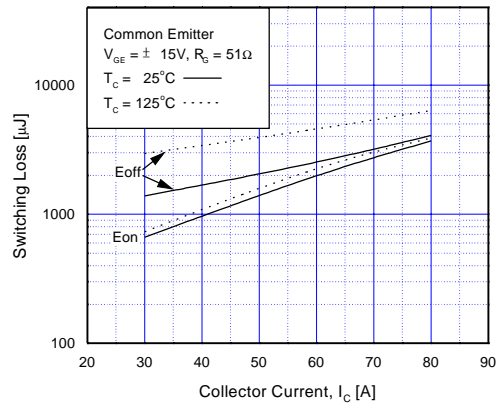
**Fig 9. Switching Loss vs. Gate Resistance**



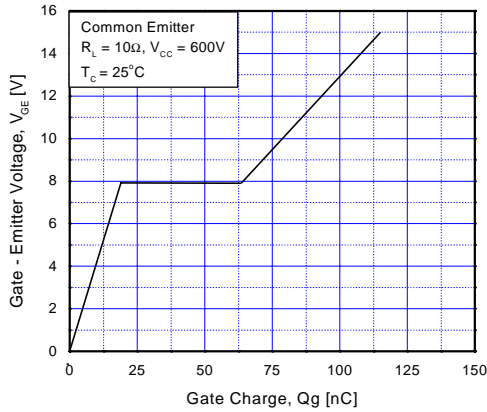
**Fig 10. Turn on Characteristics vs. Collector Current**



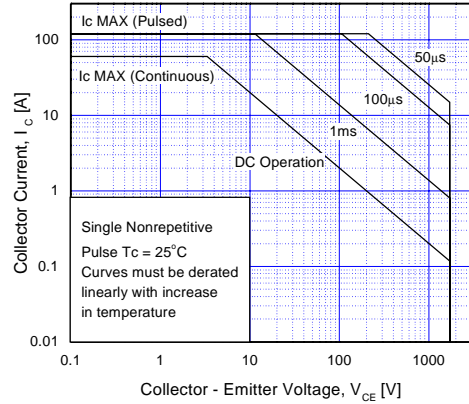
**Fig 11. Turn off Characteristics vs. Collector Current**



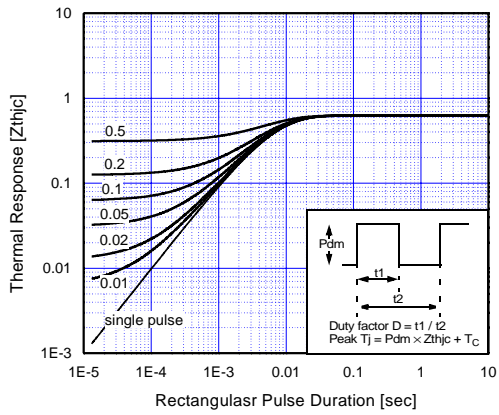
**Fig 12. Switching Loss vs. Collector Current**



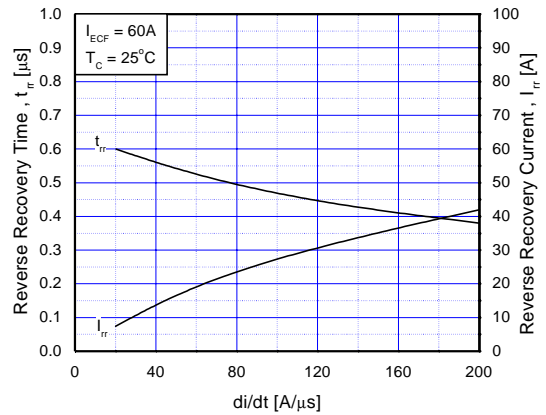
**Fig 13. Gate Charge Characteristics**



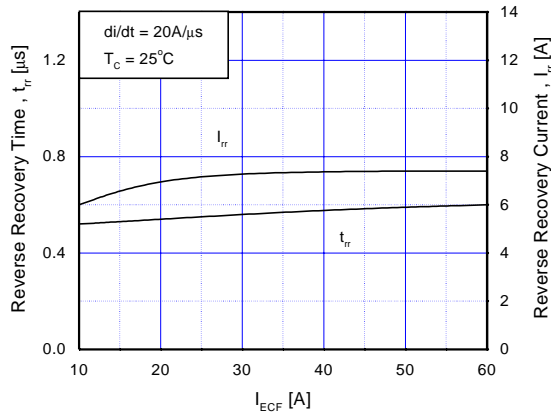
**Fig 14. Turn off SOA Characteristics**



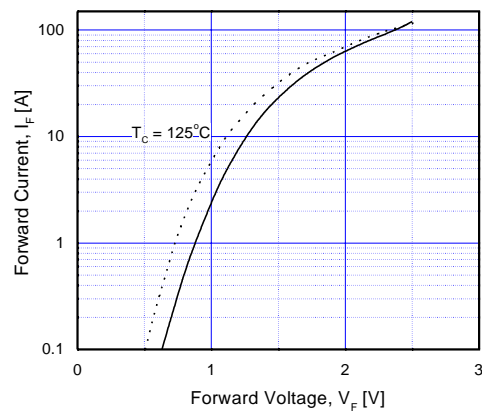
**Fig 15. Transient Thermal Impedance of IGBT**



**Fig 16. Typical Trr vs. di/dt**



**Fig 17. Typical Trr vs. Forward Current**



**Fig 18. Typical Forward Voltage Drop vs. Forward Current**

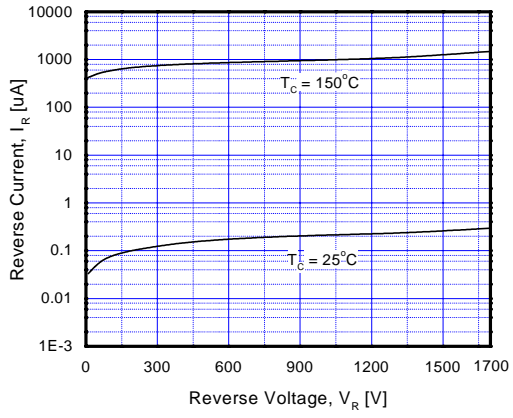


Fig 19. Reverse Current vs. Reverse Voltage

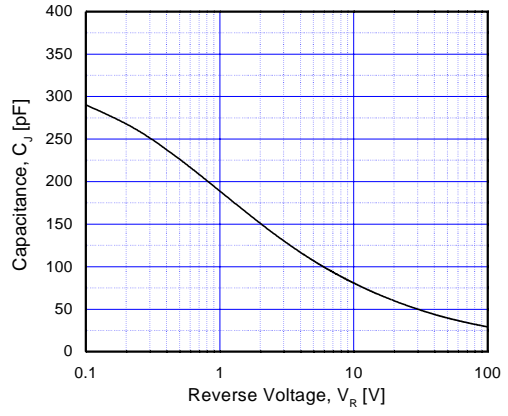
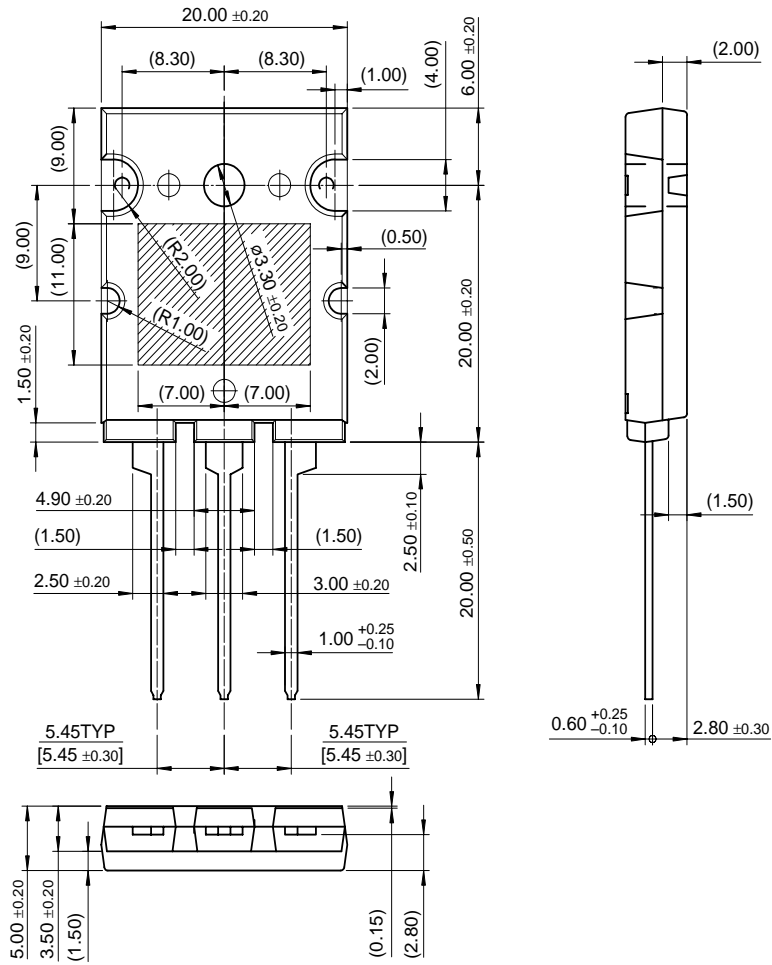


Fig 20. Capacitance vs. Reverse Voltage For Diode

# Package Dimension

## TO-264

FGL60N170D



Dimensions in Millimeters

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FGL60N170D  
Copak Discrete IGBT

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General description

Fairchild's Insulated Gate Bipolar Transistor (IGBT) provides low conduction and switching losses. FGL60N170D is designed for the Induction Heating applications.

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Features

- High Speed Switching
- Low Saturation Voltage :  $V_{CE(sat)} = 5.0$  V @  $I_C = 60A$
- High Input Impedance
- Built-in Fast Recovery Diode

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Applications

Home Appliance, Induction Heater, IH JAR, Micro Wave Oven

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FGL60N170DTU	Full Production	\$22.00	<a href="#">TO-264</a>	3	RAIL

\* 1,000 piece Budgetary Pricing

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